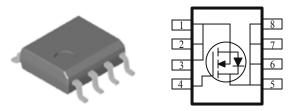
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## N-Channel 30-V (D-S) MOSFET

These miniature surface mount MOSFETs utilize High Cell Density process. Low  $r_{DS(on)}$  assures minimal power loss and conserves energy, making this device ideal for use in power management circuitry. Typical applications are PWMDC-DC converters, power management in portable and battery-powered products such as computers, printers, battery charger, telecommunication power system, and telephones power system.

- Low r<sub>DS(on)</sub> Provides Higher Efficiency and Extends Battery Life
- Miniature SO-8 Surface Mount Package Saves Board Space
- High power and current handling capability
- Low side high current DC-DC Converter applications

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$r_{DS(on)} m(\Omega)$	I <sub>D</sub> (A)		
30	$22 @ V_{GS} = 10V$	9.0		
	$36 @ V_{GS} = 4.5V$	7.0		



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C UNLESS OTHERWISE NOTED)					
Parameter		Symbol	Limit	Units	
Drain-Source Voltage		V <sub>DS</sub>	30	V	
Gate-Source Voltage		V <sub>GS</sub>	±20	v	
Continuous Drain Current <sup>a</sup>	T <sub>A</sub> =25°C	T	9.0		
Continuous Drain Current	$T_{A} = 25^{\circ}C$ $T_{A} = 70^{\circ}C$	Ъ	7.4	А	
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	30		
Continuous Source Current (Diode Conduction) <sup>a</sup>			1.6	А	
Power Dissipation <sup>a</sup>	$T_{A} = 25^{\circ}C$ $T_{A} = 70^{\circ}C$	D	3.1	W	
Power Dissipation	$T_A = 70^{\circ}C$	I D	2.0	vv	
Operating Junction and Storage Temperature Range			-55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Maximum	Units	
Maximum Junction-to-Ambient <sup>a</sup>	t <= 10 sec	$R_{\theta JA}$	40	°C/W	
	Steady-State		70	°C/W	

Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

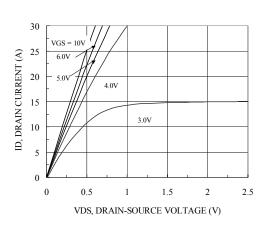
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Davamatar	Symbol Test Conditions	Limits			I Init	
Parameter	Symbol Test Conditions		Min	Тур	Max	Unit
Static						
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \text{ uA}$	1			V
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = 20 V$			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 24 V, V_{GS} = 0 V$ $V_{DS} = 24 V, V_{GS} = 0 V, T_J = 55^{\circ}C$			1 25	uA
On-State Drain Current <sup>A</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 V, V_{GS} = 10 V$	20			Α
Drain-Source On-Resistance <sup>A</sup>	r <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 9 \text{ A}$ $V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 7 \text{ A}$			22 36	mΩ
Forward Tranconductance <sup>A</sup>	g <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_D = 9 \text{ A}$		40		S
Diode Forward Voltage	V <sub>SD</sub>	$I_{S} = 2.3 \text{ A}, V_{GS} = 0 \text{ V}$		0.7		V
Dynamic <sup>b</sup>						
Total Gate Charge	Qg	V = 15 V V = 45 V		4.0		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 15 V, V_{GS} = 4.5 V,$ $I_D = 9 A$		1.1		nC
Gate-Drain Charge	Q <sub>gd</sub>			1.4		
Turn-On Delay Time	t <sub>d(on)</sub>			16		
Rise Time	t <sub>r</sub>	$V_{DD} = 25 \text{ V},  \text{R}_{\text{L}} = 25 \Omega ,  \text{ID} = 1  \text{A},$		5		
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{\text{GEN}} = 10 \text{ V}$		23		nS
Fall-Time	t <sub>f</sub>			3		
Source-Ddrain Reverse Recovery Tin	t <sub>rr</sub>	$I_F = 2.3 \text{ A}, \text{ Di/Dt} = 100 \text{ A/uS}$		41		

Notes

- a. Pulse test:  $PW \le 300$ us duty cycle  $\le 2\%$ .
- b. Guaranteed by design, not subject to production testing.

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**Figure 1. On-Region Characteristics** 

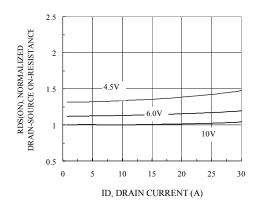


Figure 3. On Resistance Vs Vgs Voltage

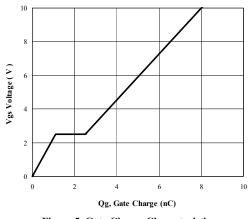
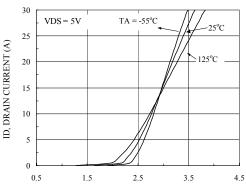


Figure 5. Gate Charge Characteristics

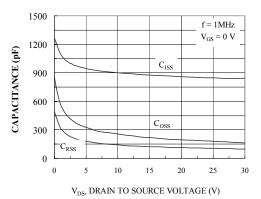
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VGS, GATE TO SOURCE VOLTAGE (V)

Figure 2. Body Diode Forward Voltage Variation

with Source Current and Temperature



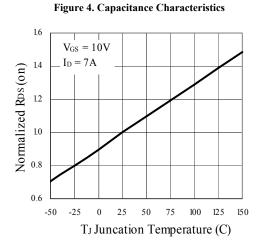
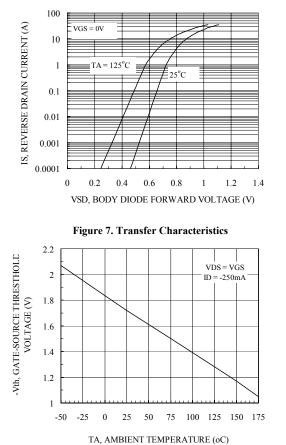


Figure 6. On-Resistance Variation with Temperature

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Typical Electrical Characteristics (N-Channel)



Typical Electrical Characteristics (N-Channel)

Figure 9. Vth Gate to Source Voltage Vs Temperature

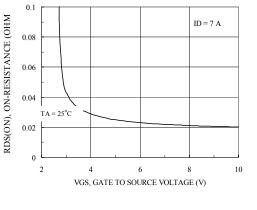


Figure 8. On-Resistance with Gate to Source Voltage

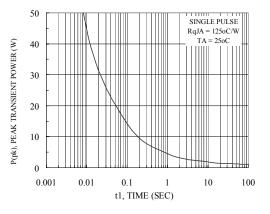
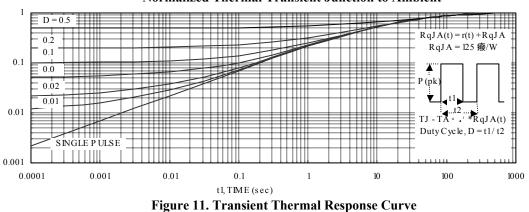


Figure 10. Single Pulse Maximum Power Dissipation



Normalized Thermal Transient Junction to Ambient

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